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EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL BC-0

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_C5171_TCoil_CELL_Ch.1013 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m³
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.6 dB
ABM1 comp = -4.32 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
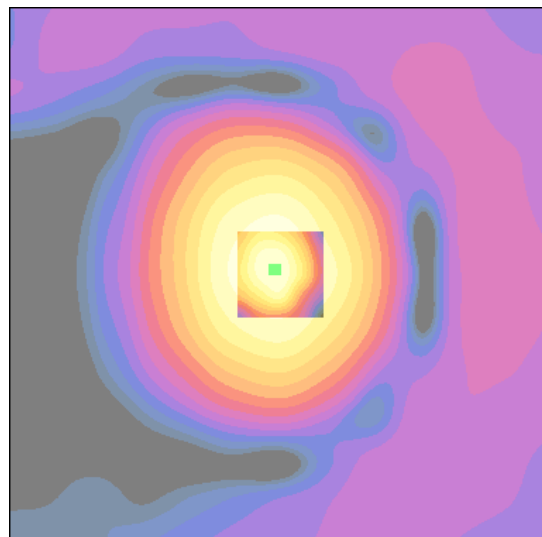Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -4.50 dB A/m
BWC Factor = 0.155041 dB
Location: 0.6, -0.4, 3.7 mm

0 dB = 300.3

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL _Ch. 1013 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 42.3 dB
ABM1 comp = -12.1 dB A/m
BWC Factor = 0.155041 dB
Location: -6.7, -3.3, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
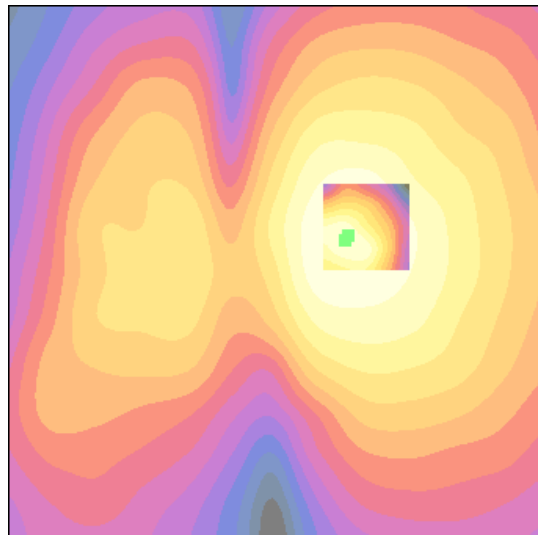Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 42.2 dB
ABM1 comp = -12.0 dB A/m
BWC Factor = 0.155041 dB
Location: -6.3, -3, 3.7 mm

0 dB = 129.8

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL _Ch. 1013 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.5 dB
ABM1 comp = -13.4 dB A/m
BWC Factor = 0.155041 dB
Location: 0, 6.7, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
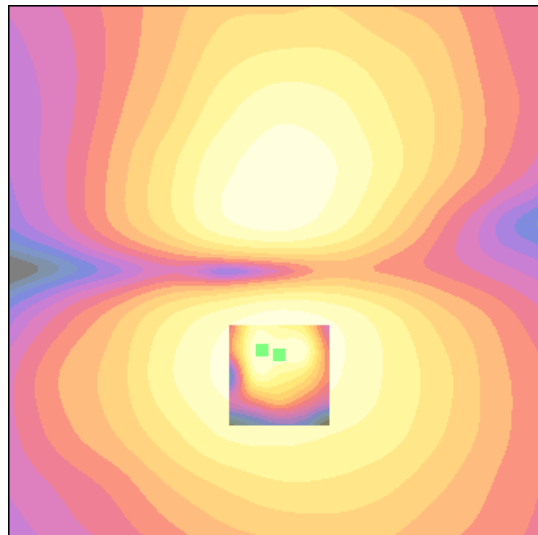Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.3 dB
ABM1 comp = -13.4 dB A/m
BWC Factor = 0.155041 dB
Location: 1.4, 6.3, 3.7 mm

0 dB = 168.8

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL_Ch.384 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.6 dB
ABM1 comp = -4.15 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
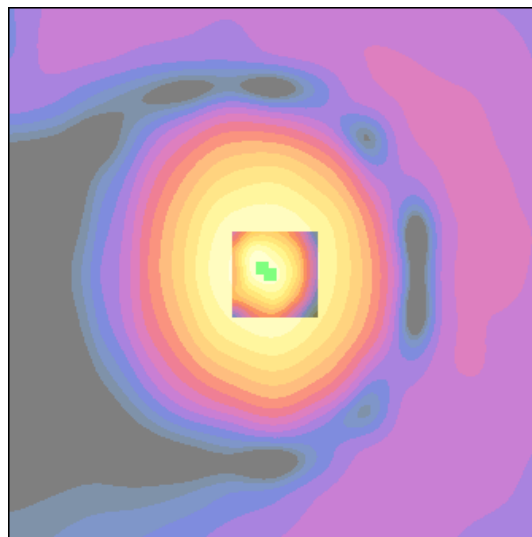Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -3.86 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, -0.6, 3.7 mm

0 dB = 302.5

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Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL _Ch.384 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.5 dB
ABM1 comp = -12.8 dB A/m
BWC Factor = 0.155979 dB
Location: -7.1, -3.3, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
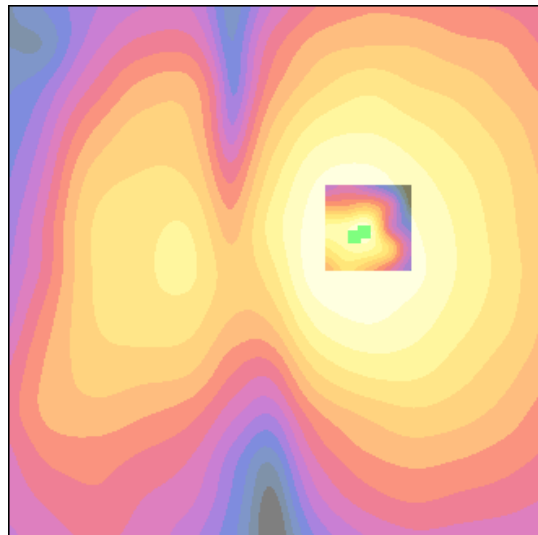Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 42.3 dB
ABM1 comp = -12.8 dB A/m
BWC Factor = 0.155979 dB
Location: -7.9, -3.8, 3.7 mm

0 dB = 118.9

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL _Ch.384 y(transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.3 dB
ABM1 comp = -13.7 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 7.1, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
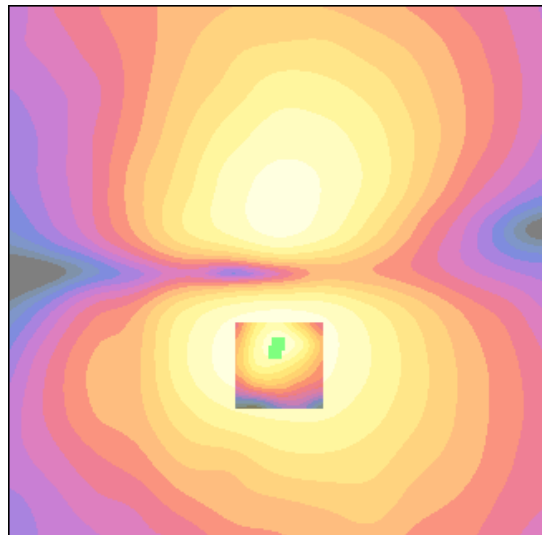Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.7 dB
ABM1 comp = -13.1 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 6.3, 3.7 mm

0 dB = 163.3

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL_Ch. 777 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.5 dB
ABM1 comp = -5.51 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, -0.8, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
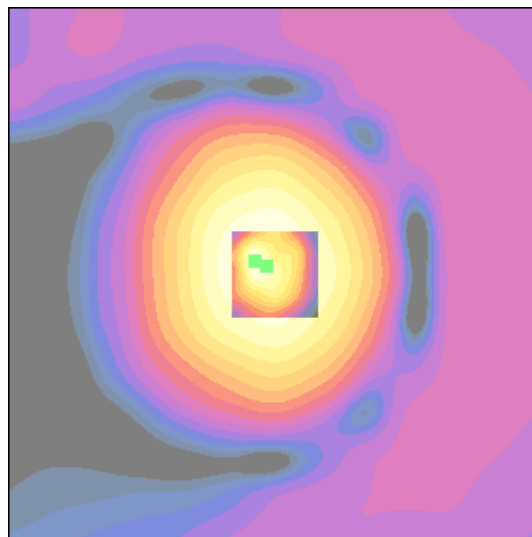Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.0 dB
ABM1 comp = -3.50 dB A/m
BWC Factor = 0.155979 dB
Location: 1.8, -1.2, 3.7 mm

0 dB = 236.6

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL_Ch. 777 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.7 dB
ABM1 comp = -12.7 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -2.9, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
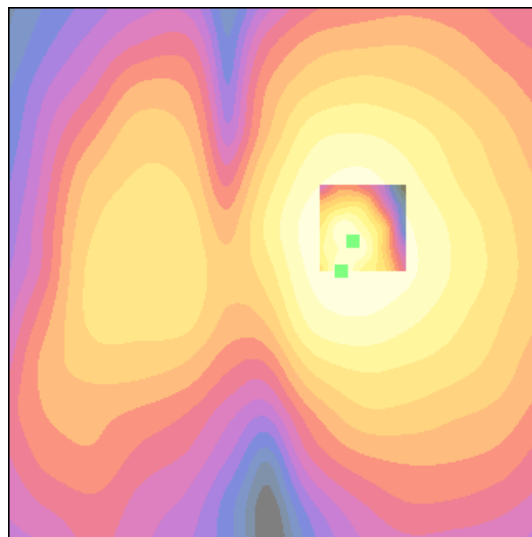Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.6 dB
ABM1 comp = -11.9 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -0.2, 3.7 mm

0 dB = 122.0

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Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_CELL_Ch. 777 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 43.8 dB
ABM1 comp = -14.1 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 5.4, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
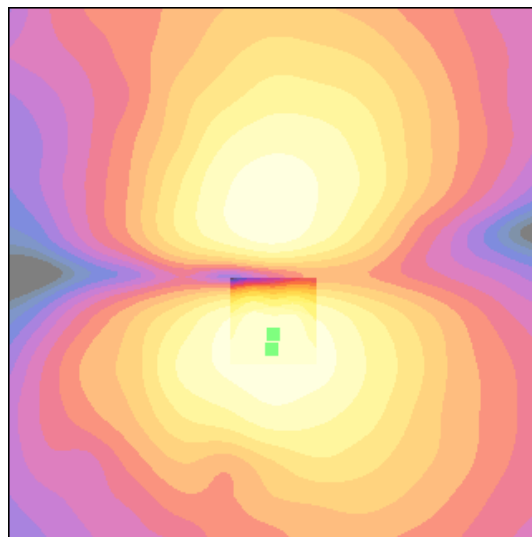Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.3 dB
ABM1 comp = -13.3 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 6.8, 3.7 mm

0 dB = 154.6

AWS

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS Ch. 25 z(axial)
Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -5.53 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -5.56 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -0.2, 3.7 mm
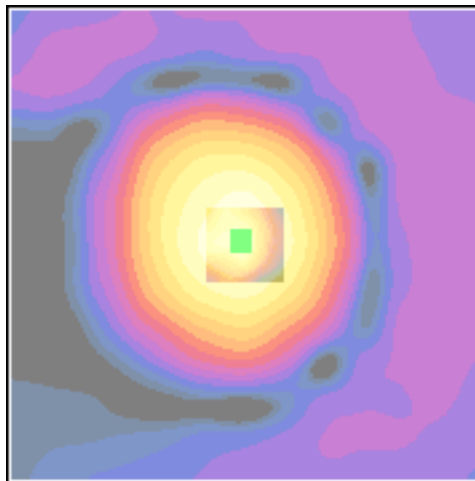
0 dB = 293.5

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 25 x(longitudinal)
Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 41.8 dB
ABM1 comp = -14.5 dB A/m
BWC Factor = 0.155041 dB
Location: -7.5, -3.8, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
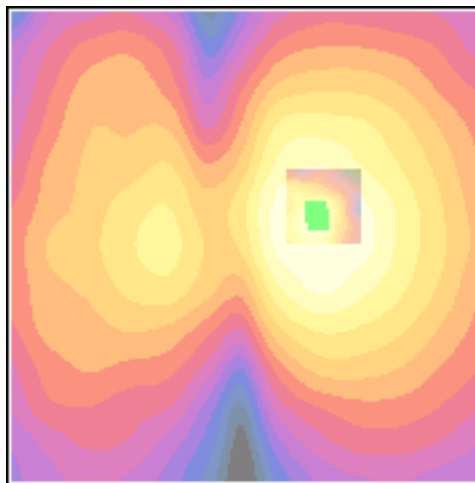Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 42.2 dB
ABM1 comp = -13.9 dB A/m
BWC Factor = 0.155041 dB
Location: -7.7, -2.8, 3.7 mm

0 dB = 122.9

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 25 y(transveral)
Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 43.9 dB
ABM1 comp = -13.4 dB A/m
BWC Factor = 0.155041 dB
Location: 0.4, -6.7, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
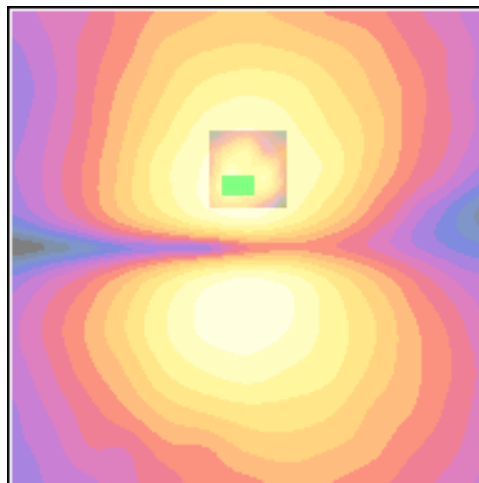Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 43.8 dB
ABM1 comp = -13.0 dB A/m
BWC Factor = 0.155041 dB
Location: 1.8, -6.7, 3.7 mm

0 dB = 157.2

Test Laboratory: COMPTEST/KYOCERA

Date: 07/24/2012

FCC_ C5171_TCoil_AWS Ch. 450 z(axial)
Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_450/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -5.55 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, -0.4, 3.7 mm

General Scans_450/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
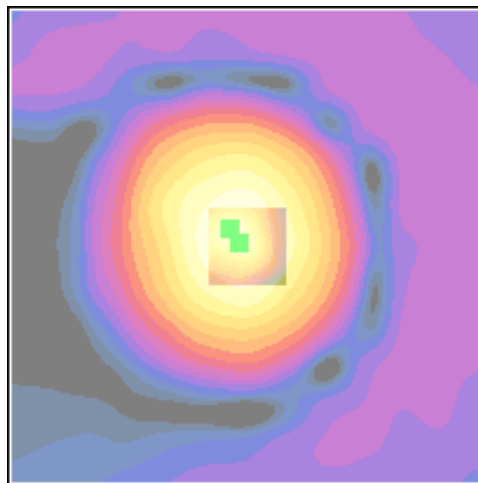Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -4.76 dB A/m
BWC Factor = 0.155041 dB
Location: 1.8, -1.8, 3.7 mm

0 dB = 288.8

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 450 x(longitudinal)
Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_450/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -14.3 dB A/m
BWC Factor = 0.155041 dB
Location: -5.8, -3.3, 3.7 mm

General Scans_450/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
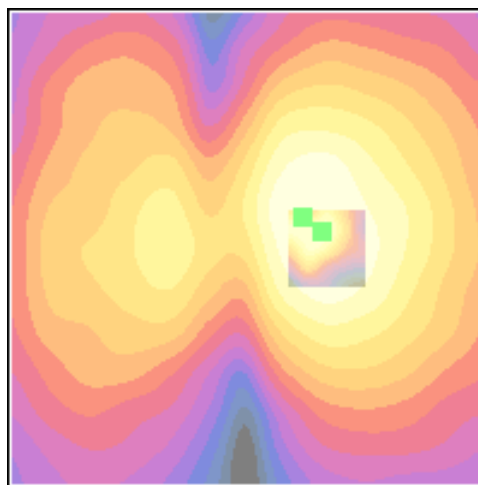Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 41.9 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155041 dB
Location: -7.7, -1.8, 3.7 mm

0 dB = 109.1

Test Laboratory: COMPTEST/KYOCERA　　　　　　　　　　　　　　Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 450 y(transveral)
Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_450/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 43.3 dB
ABM1 comp = -14.7 dB A/m
BWC Factor = 0.155041 dB
Location: 0.8, 7.5, 3.7 mm

General Scans_450/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
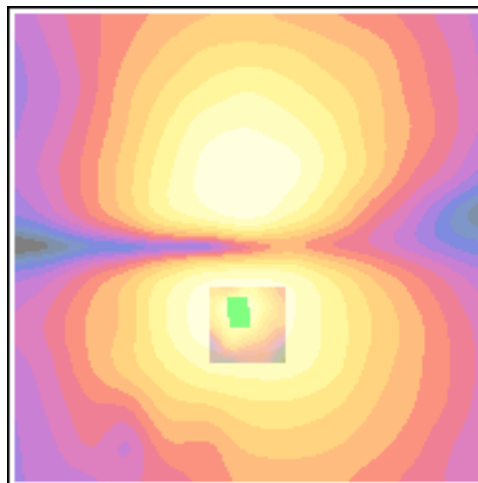Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 44.0 dB
ABM1 comp = -14.1 dB A/m
BWC Factor = 0.155041 dB
Location: 1, 6.5, 3.7 mm

0 dB = 146.2

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS Ch. 875 z(axial)
Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_875/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -5.59 dB A/m
BWC Factor = 0.155041 dB
Location: 1.3, -0.8, 3.7 mm

General Scans_875/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
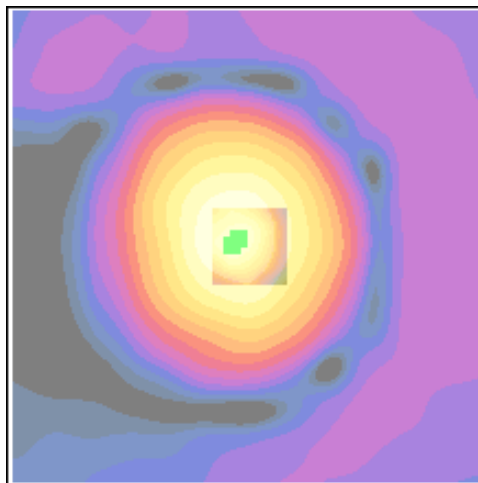Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -5.38 dB A/m
BWC Factor = 0.155041 dB
Location: 1.8, -0.2, 3.7 mm

0 dB = 289.4

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 875 x(longitudinal)
Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_875/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 41.8 dB
ABM1 comp = -14.1 dB A/m
BWC Factor = 0.155041 dB
Location: -7.5, -2.5, 3.7 mm

General Scans_875/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
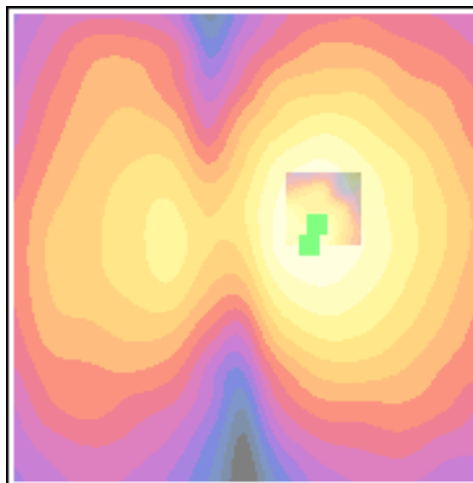Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 42.2 dB
ABM1 comp = -13.1 dB A/m
BWC Factor = 0.155041 dB
Location: -6.7, -0.2, 3.7 mm

0 dB = 122.8

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_AWS_Ch. 875 y(transveral)
Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_875/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 43.9 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155041 dB
Location: 0, -7.9, 3.7 mm

General Scans_875/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155041 dB
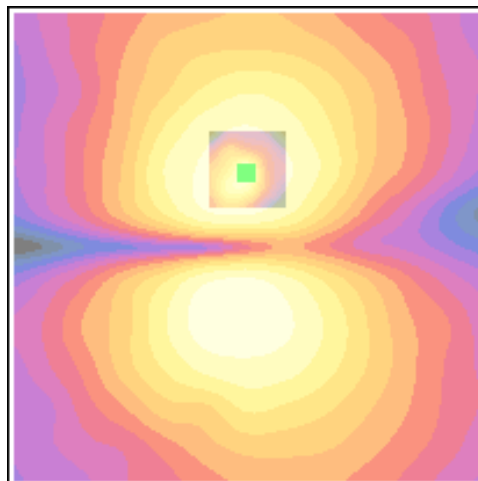Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:
ABM1/ABM2 = 44.5 dB
ABM1 comp = -12.9 dB A/m
BWC Factor = 0.155041 dB
Location: 0.2, -7.9, 3.7 mm

0 dB = 156.3

PCS

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS Ch. 25 z(axial)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -4.48 dB A/m
BWC Factor = 0.157003 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
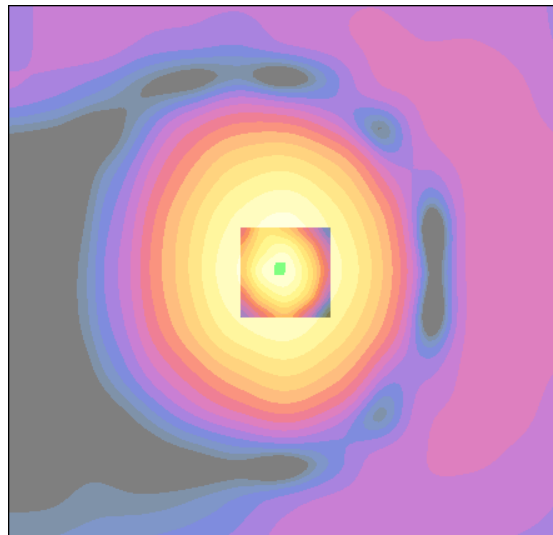Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.5 dB
ABM1 comp = -4.59 dB A/m
BWC Factor = 0.157003 dB
Location: 0.6, -0.2, 3.7 mm

0 dB = 261.3

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS_ Ch. 25 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.5 dB
ABM1 comp = -12.4 dB A/m
BWC Factor = 0.157003 dB
Location: -7.1, -2.1, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
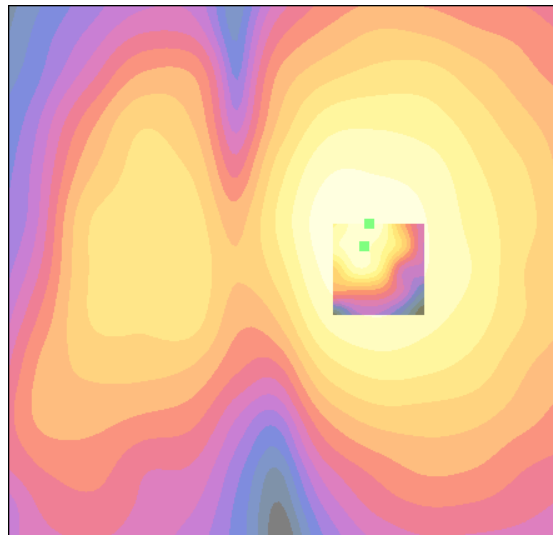Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.5 dB
ABM1 comp = -12.9 dB A/m
BWC Factor = 0.157003 dB
Location: -7.5, -4, 3.7 mm

0 dB = 118.4

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS_ Ch. 25 y(transversal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.1 dB
ABM1 comp = -13.6 dB A/m
BWC Factor = 0.157003 dB
Location: 0.4, 6.2, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.157003 dB
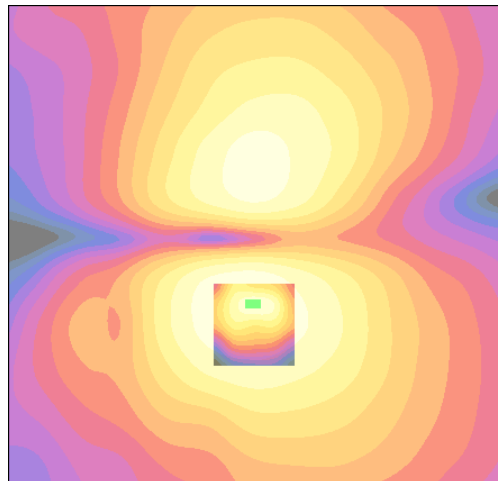Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.4 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.157003 dB
Location: -0.2, 6.3, 3.7 mm

0 dB = 160.0

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS_ Ch. 600 z(axial)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -4.96 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -0.8, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
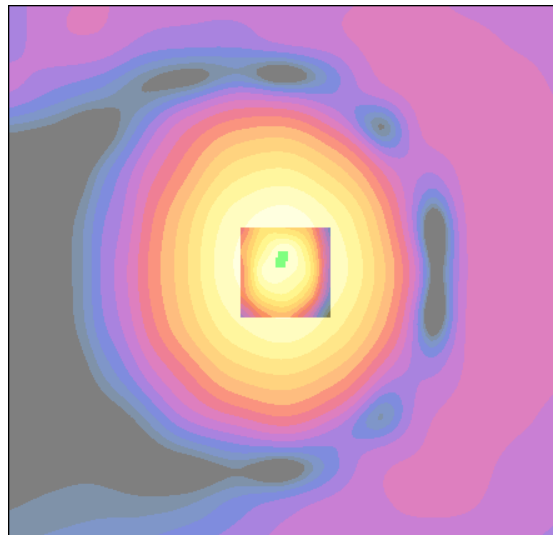Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -4.71 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, -1.4, 3.7 mm

0 dB = 247.7

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS _Ch. 600 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.5 dB
ABM1 comp = -12.5 dB A/m
BWC Factor = 0.155979 dB
Location: -7.1, -2.9, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
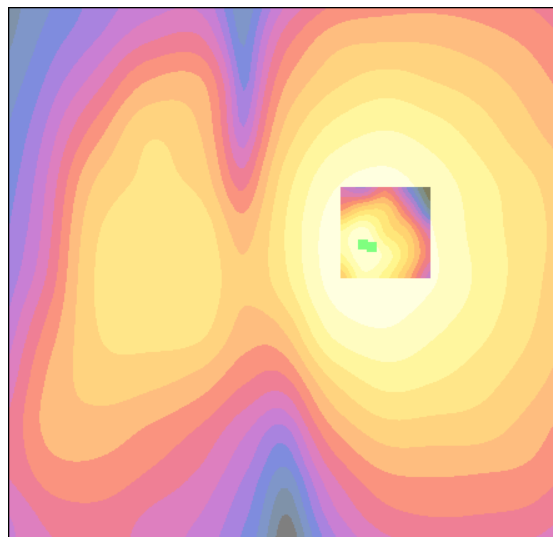Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.7 dB
ABM1 comp = -11.9 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -3.2, 3.7 mm

0 dB = 118.2

Test Laboratory: COMPTEST/KYOCERA   Date: 07/24/2012

FCC_ C5171_TCoil_PCS_ Ch. 600 y(transversal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.0 dB
ABM1 comp = -13.9 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 7.1, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
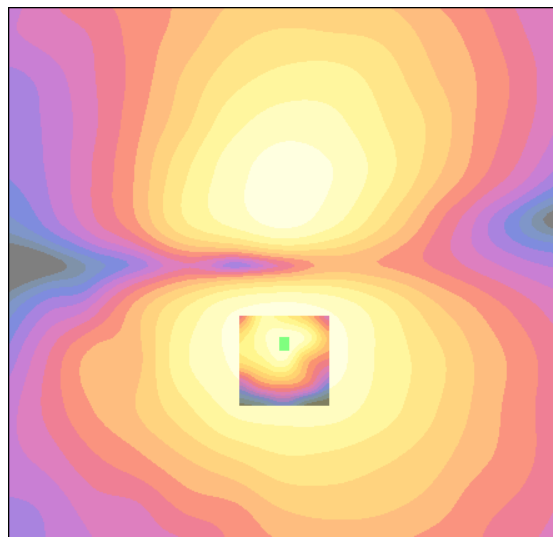Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.1 dB
ABM1 comp = -13.7 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 6.7, 3.7 mm

0 dB = 159.3

Test Laboratory: COMPTEST/KYOCERA   Date: 07/25/2012

FCC_ C5171_TCoil_PCS_Ch. 1175 z(axial)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.0 dB
ABM1 comp = -5.50 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -1.7, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
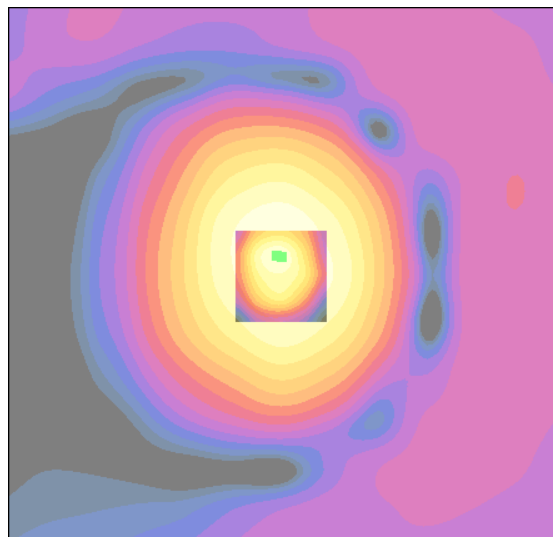Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -4.26 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -1.8, 3.7 mm

0 dB = 223.9

Test Laboratory: COMPTEST/KYOCERA   Date: 07/25/2012

FCC_ C5171_TCoil_PCS_ Ch. 1175 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.3 dB
ABM1 comp = -12.3 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -1.7, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
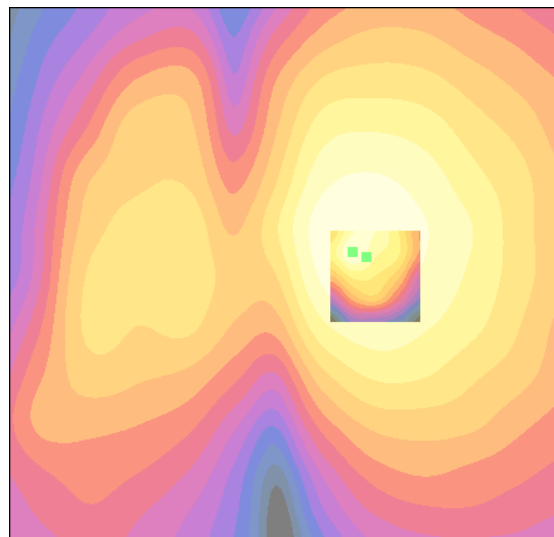Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.2 dB
ABM1 comp = -11.7 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -2.2, 3.7 mm

0 dB = 115.7

Test Laboratory: COMPTEST/KYOCERA   Date: 07/25/2012

FCC_ C5171_TCoil_PCS_ Ch. 1175 y(transversal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn675,Calibrated: 5/23/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.1 dB
ABM1 comp = -13.5 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 5.8, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
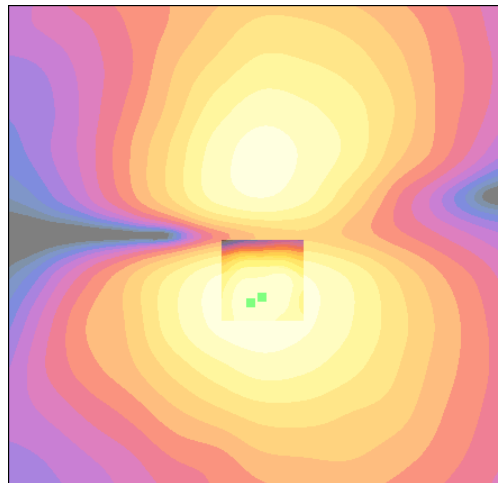Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 44.1 dB
ABM1 comp = -13.3 dB A/m
BWC Factor = 0.155979 dB
Location: 1.2, 6.4, 3.7 mm

0 dB = 160.2